

THERMAL MANAGEMENT MATERIALS



As devices run at higher powers and the need for thermal management becomes greater, materials with heat dissipation superior to organic silicon grease type material are needed. AIM offers advanced materials for these types of applications. These products are utilized when the outgassing of thermal greases is problematic, the conductivity of thermal greases is insufficient for the heat dissipation needed, or the interface material also needs to serve as a mechanical connection.



Indium and indium alloys are the ultimate thermal management materials, offering exceptional ductility and superior heat dissipation. These elements and alloys are available in powder for fillers, foils, wire and custom fabricated preforms to fit any requirement.

Thermal foils are alloy laminated foils designed to provide exceptional co-planarity conformity while reducing oxide content. This yields a consistent, reproducible thermal management interface.

Material	Melting Point (C)		Conductivity	Composition
	Solidus	Liquidus	(W/m.K @ 85C)	(weight %)
AIM 141	60	60		In51.5/Sn16.5/Bi32
AIM 118	118	118	34	In52/Sn48
AIM 125	118	125		In50/Sn50
AIM 130	120	130		In40/Sn40/Pb20
AIM 146	146	146	73	In97/Ag3
AIM 149	148	149	43	In80/Pb15/Ag5
AIM 161	153	161		In12/Sn70/Pb18
AIM 156	156.6	156.6	86	In100

For additional information please contact AIM at
 + 401 463-5605
 + 401 463-0203 Fax
 or visit us on the web at
www.aimsolder.com

Please contact AIM for additional information on our thermal management materials.